BOARD TITLE: PAINEL_MEB

AUTHOR: CCB

CODE NUMBER: REVISION: 1 02

LAYER STACKUP:

TOP & BOTTOM: SIGNAL + GND PLANE

GENERAL NOTES:

1. LAMINATE SPECIFICATIONS:

- TOTAL THICKNESS: 1.6 mm +/- 0.2 mm
- LAYER NUMBERS: 2
- Cu THICKNESS (FINISHED):

1 oz / 1 oz

- RAW MATERIAL: FR-4
- TG MIN.: 150 °C
- TD MIN.: 310 °C

2, HOLE CHARACTERISTICS:

- PLATED HOLE TOLERANCE: +/- 0.1 mm
- NON PLATED HOLE TOLERANCE: +/- 0.1 mm
- DISPLACEMENT: 0.1 mm MAX.
- Cu THICKNESS ON HOLE: 20 um + SnPb MIN.

3. FINISHING:

- HOT AIR SOLDER LEVELING (HASL) - SnPb

4. SILKSCREEN MASK:

REVISIONS DESCRIPTION:

1 00 - Initial revision - Jun/4/2016

1 02 - Smd bicolor leds for SpW channels,

- WHITE (THERMAL CURE EPOXY)

5. SOLDER MASK:

- BOTH SIDES
- GREEN EPOXY THERMAL CURE OR PHOTO IMAGEABLE

1 01 - Rtcc + mac address chip, with cr2032 battery - Nov/16/2016

lvds driver/receiver for sinc-out/sinc-in - Jun/2017

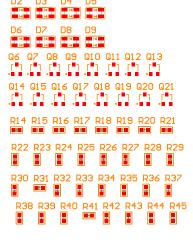
- IONIC CONTAMINATION AFTER SOLDERING: 14 ug NaCl / in2 MAX.
- COVER VIAS WITH SOLDER MASK ON BOTH SIDES

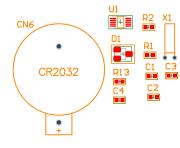
6. SPECIFIED STANDARDS:

- IPC-6011 CLASS 2 / IPC-6012 CLASS 2 / IPC-A-600 CLASS 2

7. ADDITIONAL NOTES:

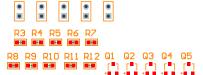
- DIMENSIONAL TOLERANCE: +/- 0.2 mm
- ELECTRICAL TESTS ARE MANDATORY
- GERBER MODIFICATIONS ARE ONLY ALLOWED WITH EXPLICIT AUTHOR / RESPONSIBLE AUTHORIZATION

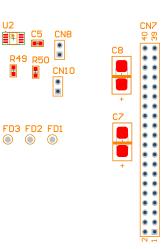






CN2 CN3 CN4 CN5 CN1









PAINEL MEB - 1 02 - 2017/JUN

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